

---

# Noise Driven In Package Decoupling Capacitor Optimization for Power Integrity

---

Jun Chen and Lei He

Design Automation Laboratory, UCLA

---

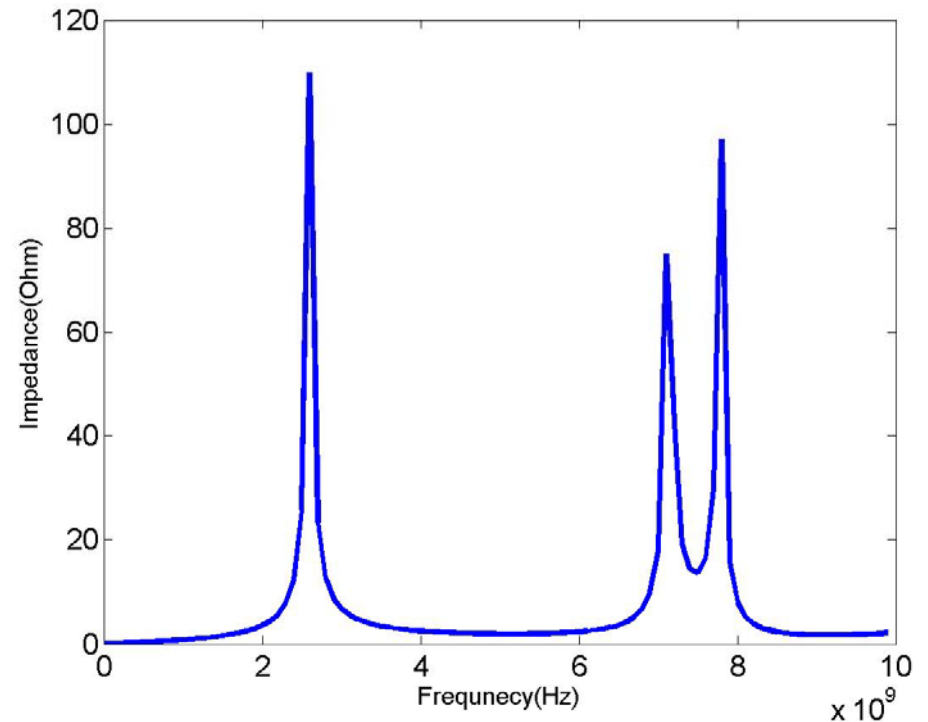


# Outline

- ◆ Introduction
- ◆ Electrical models
- ◆ Incremental impedance computation and noise computation
- ◆ Optimization results
- ◆ Conclusion

# Power Integrity

- ◆ Noise in power delivery system (PDS)
  - IR drop
  - dI/dt drop
  - Resonance
- ◆ Challenges in advanced high-performance package
  - High power consumption
    - ◆ Large current
  - High clock frequency
    - ◆ Large inductive effects and resonance
  - Large number of I/O's
    - ◆ SSN



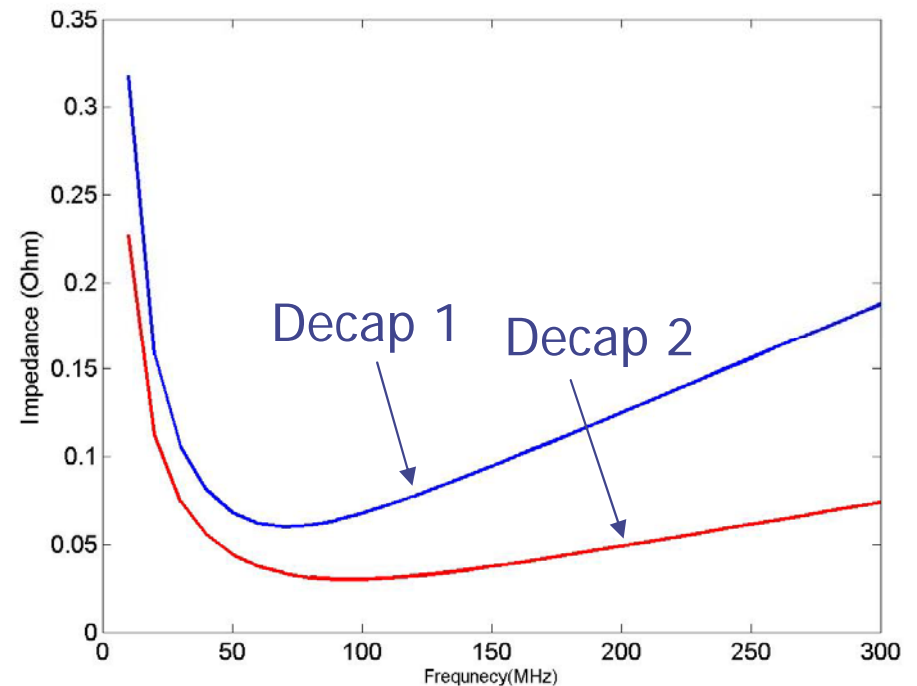
# Decoupling capacitors

## ◆ Improve power integrity with decoupling capacitors

- Low impedance path
- Temporary current source

## ◆ In-Package decoupling capacitors for package

- Discrete elements
- Discrete ESC, ESL, ESR
- Different effective frequencies
- Different in costs



# In-Package decoupling capacitor optimization problem

## ◆ Optimization problem for in-package decoupling capacitors

- Given a package and chip I/Os
- Find the best types and locations of decoupling capacitors
- Such that the cost is minimized
- Subject to SSN noise bound

## ◆ Challenges

- Large number of I/O's and possible locations and types for decoupling capacitors
- Complex model with inductance
- Non-monotonic solution space
  - ◆ More decoupling capacitors do not always lead to better integrity
  - ◆ Locations closer to I/O does not always lead to better solutions
  - ◆ Hard to use mathematic programming for optimization

# Existing Work

## ◆ Manual trial-and-error approaches

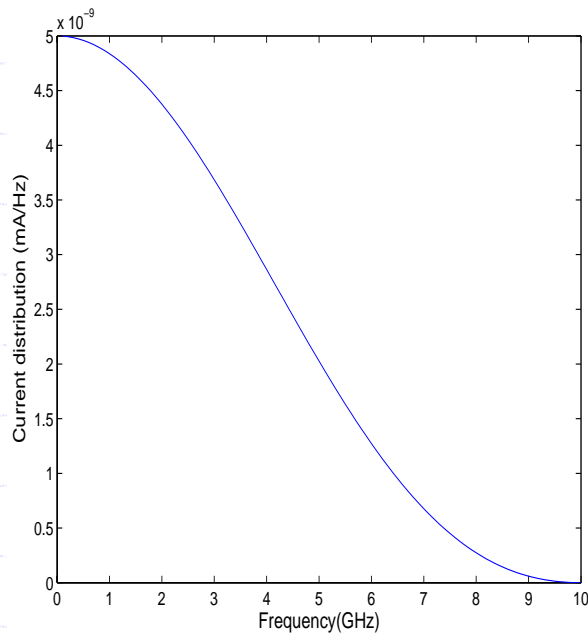
- [Chen et al., ECTC '96]
- [Yang et al., EPEP 2002]

## ◆ Automatic optimization

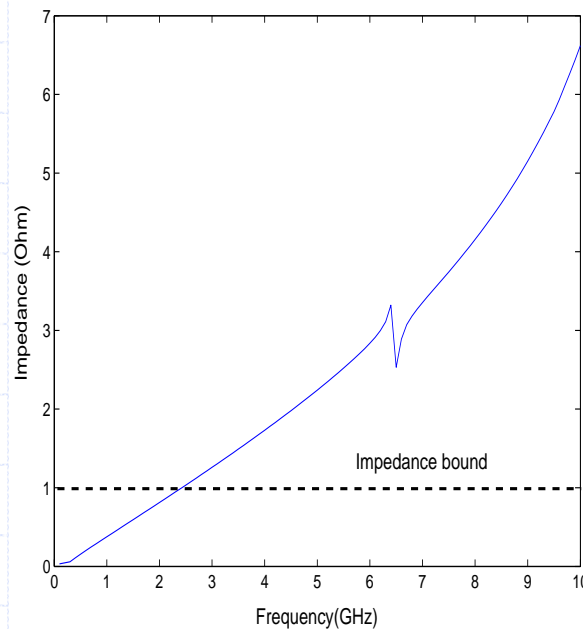
- [Kamo et al., EPEP 2000], [Hattori et al., EPEP 2002]
  - ◆ Ignore ESL and ESR.
- [Zheng et al., CICC 2003]
  - ◆ Use impedance as noise metric

# Limitation of Impedance Metric

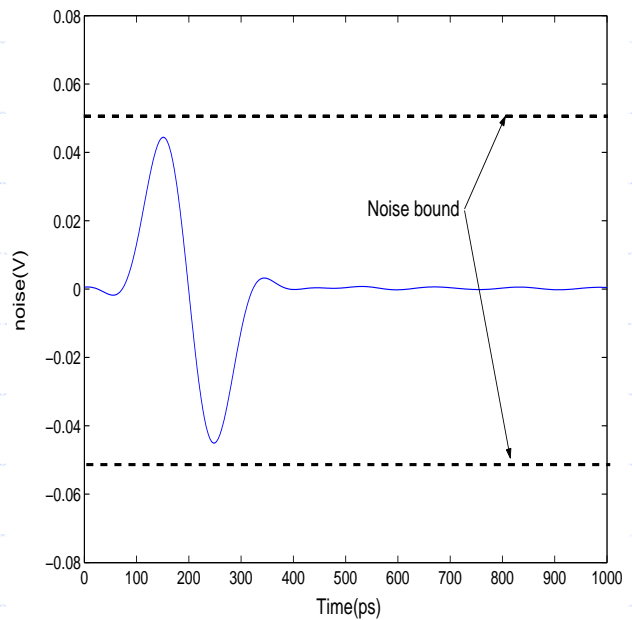
- ◆ Traditional noise bound can not capture noise accurately
- ◆ Will Lead to large over-design
- ◆ Difficult to consider coupling noise between ports



$I(f)$



$Z(f)$



$V_n(t)$



# Our contributions

## ◆ Efficient noise model

- Efficient incremental impedance computation
  - ◆ Time complexity:  $O(n^2)$  vs  $O(n^3)$
- Explicit time-domain noise metric
  - ◆ FFT

## ◆ Optimize both types and locations of decoupling capacitors based on explicit noise model

- 3x smaller cost compared to impedance based approach
- 10x speedup compared to admittance matrix inversion based method



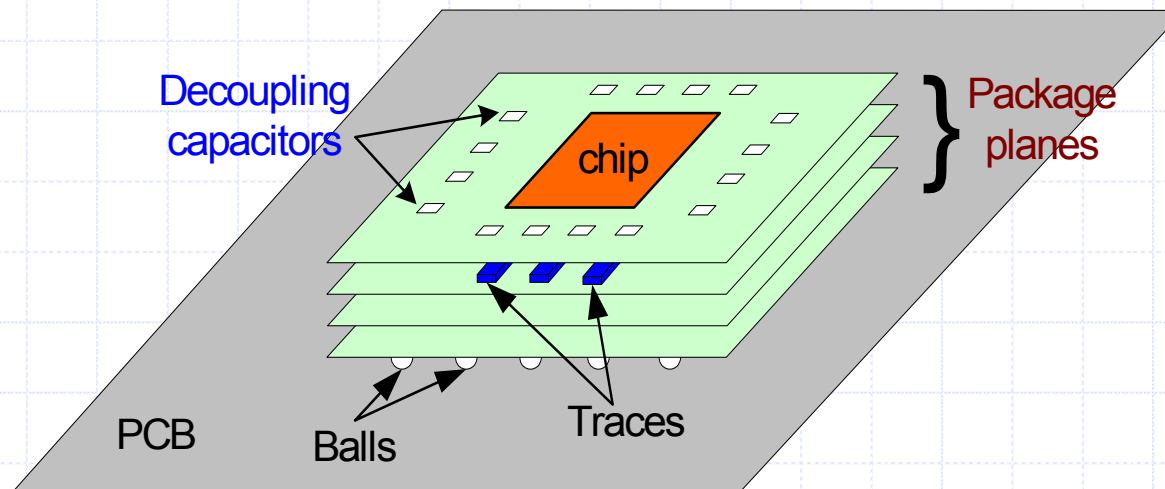
# Outline

- ◆ Introduction
- ◆ **Electrical models**
- ◆ Incremental impedance computation and noise computation
- ◆ Optimization results
- ◆ Conclusion

# Package model

## ◆ IC package

- Multiple signal layers, power planes and ground planes
- Planes stapled with Vias



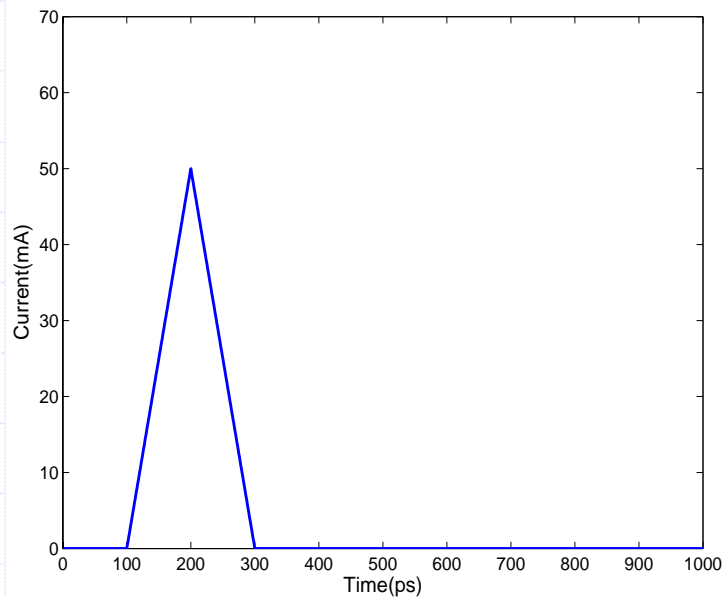
# Macromodel of PDS

- ◆ Given ports
  - Known I/O locations
  - Possible decoupling capacitor locations
  
- ◆ Pre-compute macromodel of PDS before optimization at sampling frequency  $f_k$ 
  - Impedance matrix  $Z(f_k)$ 
    - ◆ Detailed PEEC model+model order reduction
  - Field solver, measurement, ...
  - Not limited to package
    - ◆ May include VRM, PCB and on-chip P/G grid.

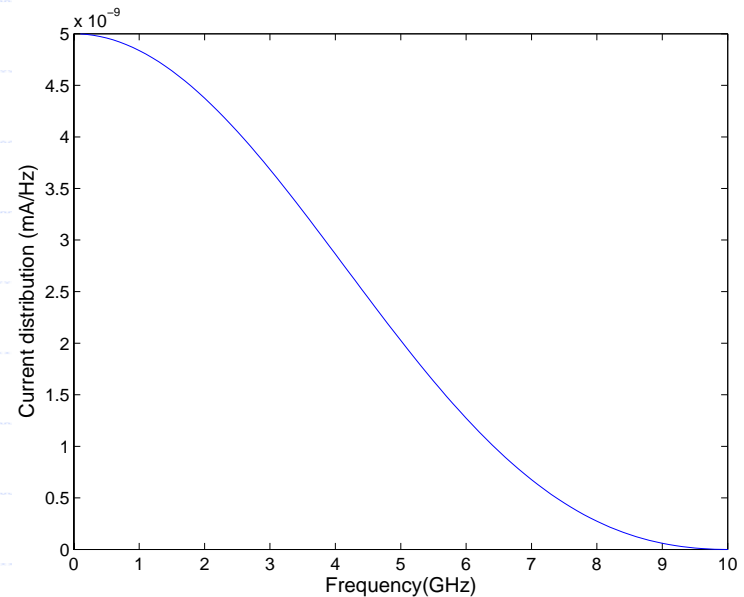
# Model of Switching Current

## ◆ I/O cells

- Pre-characterize time dependent switching current
- Transform waveform into frequency domain



Time domain

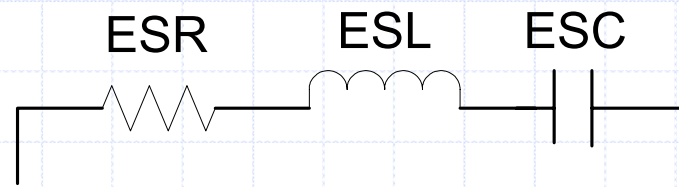


Frequency domain

# Decoupling capacitor model

## ◆ Decoupling capacitor

- ESC, ESR and ESL



- Pre-compute frequency dependent impedance

$$Z_d(\omega) = \text{ESR} + \frac{1}{j\omega\text{ESC}} + j\omega\text{ESL}$$

# Outline

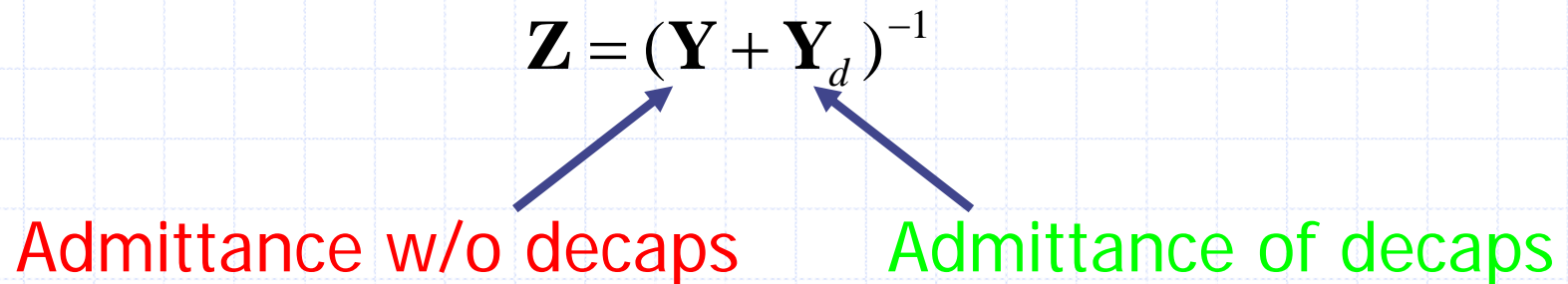
- ◆ Introduction
- ◆ Electrical models
- ◆ Incremental impedance computation and noise computation
- ◆ Optimization results
- ◆ Conclusion

# Existing Approach for Impedance Updating

- ◆ To compute the noise accurately, impedance at a large number of frequencies needs to be computed
- ◆ With pre-computed macromodel, [Zhao and Mandhana, EPEP2004]

$$\mathbf{Z} = (\mathbf{Y} + \mathbf{Y}_d)^{-1}$$

Admittance w/o decaps      Admittance of decaps



- ◆ Disadvantages:
  - Involving inversion of large matrix at each frequency
    - ◆  $O(n^3)$  complexity
  - Compute all the  $Z_{ij}$  each iteration.
    - ◆ Better solution: update  $Z_{ij}$  when necessary



# Incremental impedance updating with decoupling capacitor

- ◆ Update each  $Z_{ij}$  individually.
- ◆ Consider one decoupling capacitor each time.
- ◆ When adding one decoupling capacitor  $Z_d$  at port  $k$

$$\hat{Z}_{ij} = Z_{ij} - \frac{Z_{ik}Z_{kj}}{Z_{kk} + Z_d}$$

- ◆ When removing one decoupling capacitor  $Z_d$  at port  $k$

$$\hat{Z}_{ij} = Z_{ij} - \frac{Z_{ik}Z_{kj}}{Z_{kk} - Z_d}$$

- ◆ Complexity is  $O(1)$  for one port.

# Time complexity

- ◆ For entire system, with one or a few decoupling capacitors changed
  - $O(n_p^2)$ :  $n_p$  is the number of ports
  - Existing work:  $O(n_p^3)$
- ◆ Suitable for trial-and-error or iterative methods
  - Only a few decoupling capacitors changed in each iteration
  - Able to compute only impedance of I/O ports before updating rest ports

# Noise Calculation

## ◆ FFT methods

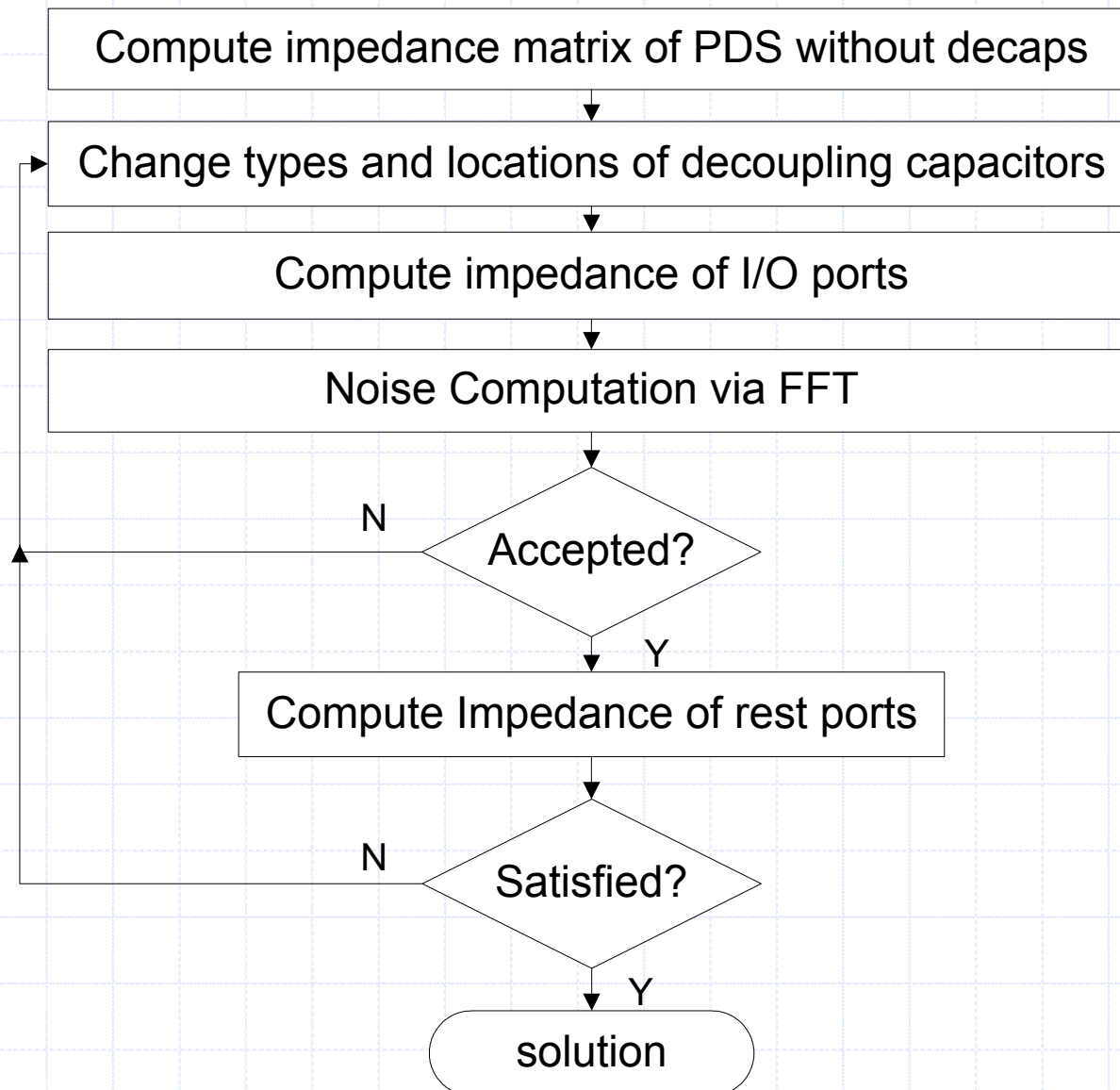
- Impedance is computed at a large number of frequencies
- Frequency components of noise from port  $j$  to port  $i$

$$V_{ij}(f_k) = Z_{ij}(f_k) \bullet I_j(f_k)$$

## ◆ Worst case noise

- Consider coupling noise from other ports
- Superposition

# Efficient General Iterative Optimization Flow



$$O(n_{I/O}^2)$$

$$O(n_p^2)$$

# Outline

- ◆ Introduction
- ◆ Electrical models
- ◆ Incremental impedance computation and noise computation
- ◆ Optimization results
- ◆ Conclusion

# Algorithm

## ◆ Simulated annealing with objective function

$$F(p_i, c_i) = \alpha \sum_{i \in I_0} p_i + \beta \sum_j c_i$$

- ◆  $p_i$ : Penalty function for noise violation
- ◆  $c_i$ : cost of decoupling capacitor
- ◆  $\alpha, \beta$ : weights

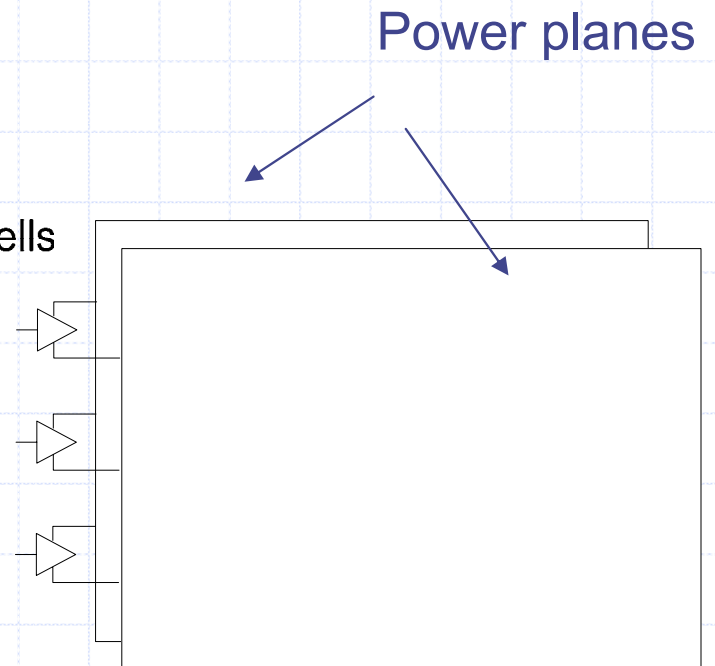
# Example

- ◆ 4 types of decoupling capacitors
- ◆ 3 I/O ports
  - Each connected to 10 I/O cells
- ◆ 90 possible locations for decoupling capacitors
- ◆ Total 93 ports
- ◆ Worst case noise bound: 0.35V

Type	1	2	3	4
ESC(nF)	50	100	50	100
ESR( $\Omega$ )	0.06	0.06	0.03	0.03
ESL(pH)	100	100	40	40
Price	1	2	2	4

[Zheng et al., CICC 2003]

Chip I/O Cells





# Experiment results: noise based

0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	0	0	0	0
0	0	0	1	0	0	0	0	0	0	0
0	1	0	0	0	3	0	0	0	0	3
1	0	0	1	0	4	0	2	3	0	1
0	0	0	0	0	0	0	0	0	0	0

Chip

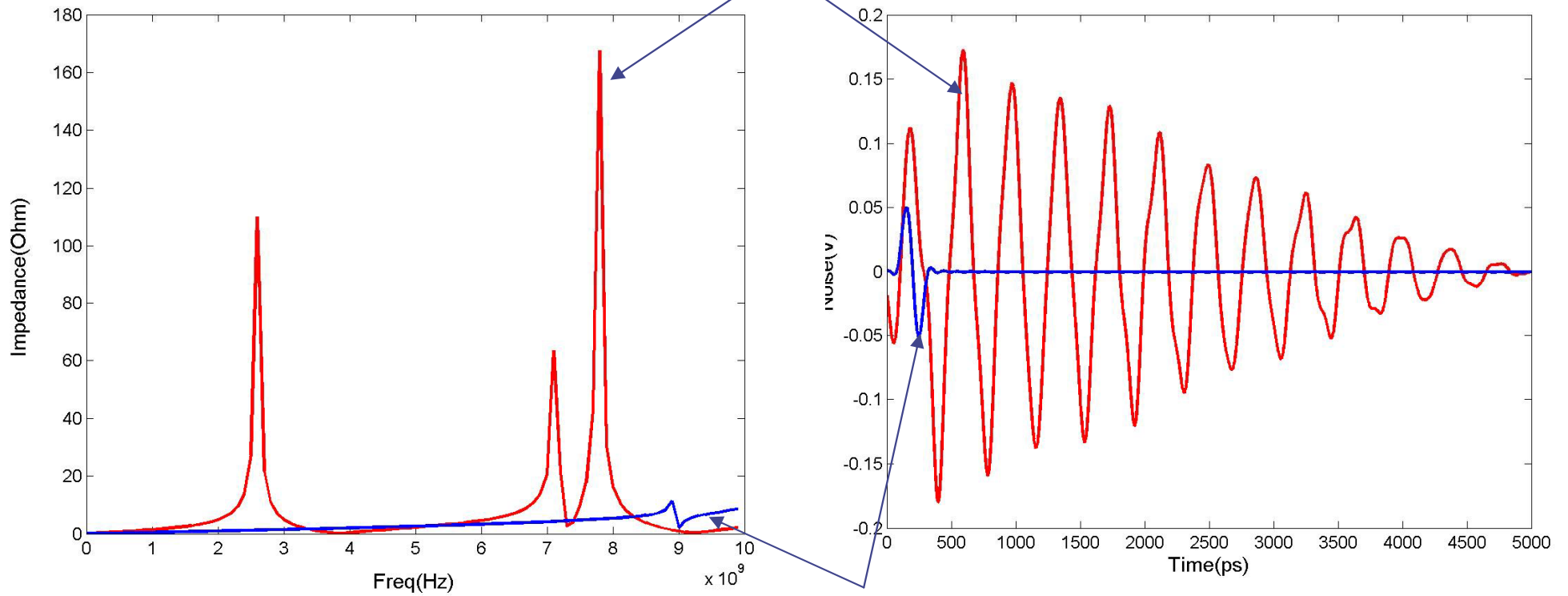
◆ Cost=20

Type	1	2	3	4
ESC(nF)	50	100	50	100
ESR( $\Omega$ )	0.06	0.06	0.03	0.03
ESL(pH)	100	100	40	40
Price	1	2	2	4

port	1	2	3
before optimization	2.52V	2.49V	2.48V
after optimization	0.344V	0.343V	0.344V

# Impedance and Noise

Before optimization

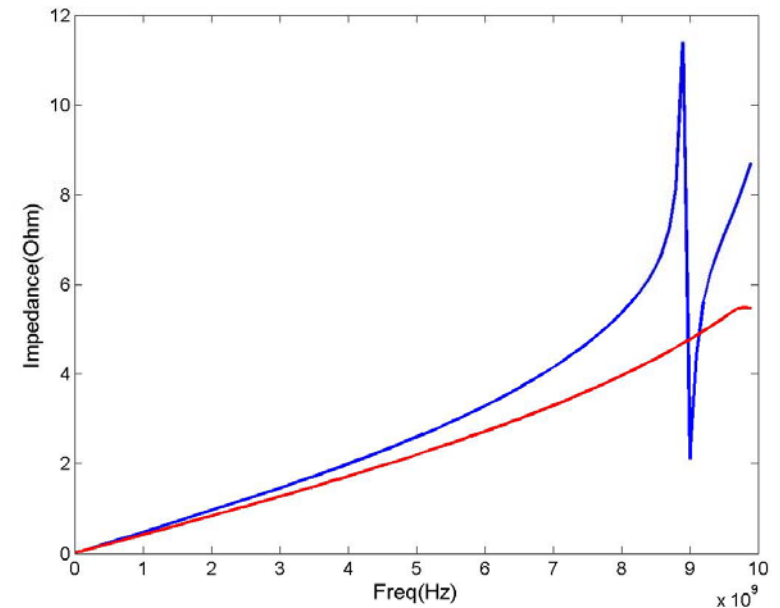


After optimization

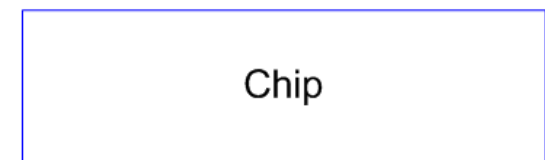
# Comparison: Impedance based approach

- ◆ **Cost=72**
  - **3X** larger than noise based
- ◆ Impedance bound is not met but noise bound has already been met.
  - **Overdesign**

port	1	2	3	bound
Maximum Impedance	5.31Ω	5.59Ω	7.12Ω	0.7Ω
worst-case noise	0.256V	0.302V	0.284V	0.35V



0	0	0	0	0	0	0	0	0	0	0
0	0	0	0	4	0	0	0	0	0	0
0	0	0	0	0	0	0	4	0	0	0
0	0	0	0	0	0	0	4	0	0	0
1	0	0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	1	0	4	1
0	0	0	0	0	2	0	0	2	3	4
0	0	2	4	1	2	0	4	2	2	1
2	4	3	3	1	1	0	1	4	1	4
0	0	0	0	0	0	0	0	0	0	0



# Runtime Comparison

1	Noise based via incremental impedance computation
2	Noise based via admittance matrix inversion [Zhao et al, EPEP 2004]
3	Impedance based [Zheng et al, CICC 2003]

approach	1	2	3
ports	93	93	20
iterations	5881	5403	1920
runtime(s)	389.5	4156.1	2916
avg. runtime(s)	0.0662	0.7692	1.519

**10x** speedup compared to method based on admittance matrix inversion

# Conclusion

- ◆ Proposed efficient noise computation model based on incremental impedance updating
- ◆ Proposed efficient noise driven decoupling capacitor optimization algorithm
  - 3X smaller cost
  - 10x speedup
- ◆ Demonstrated impedance based approach leads to large overdesign.